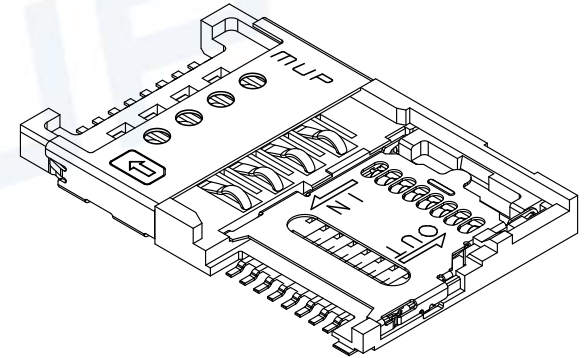
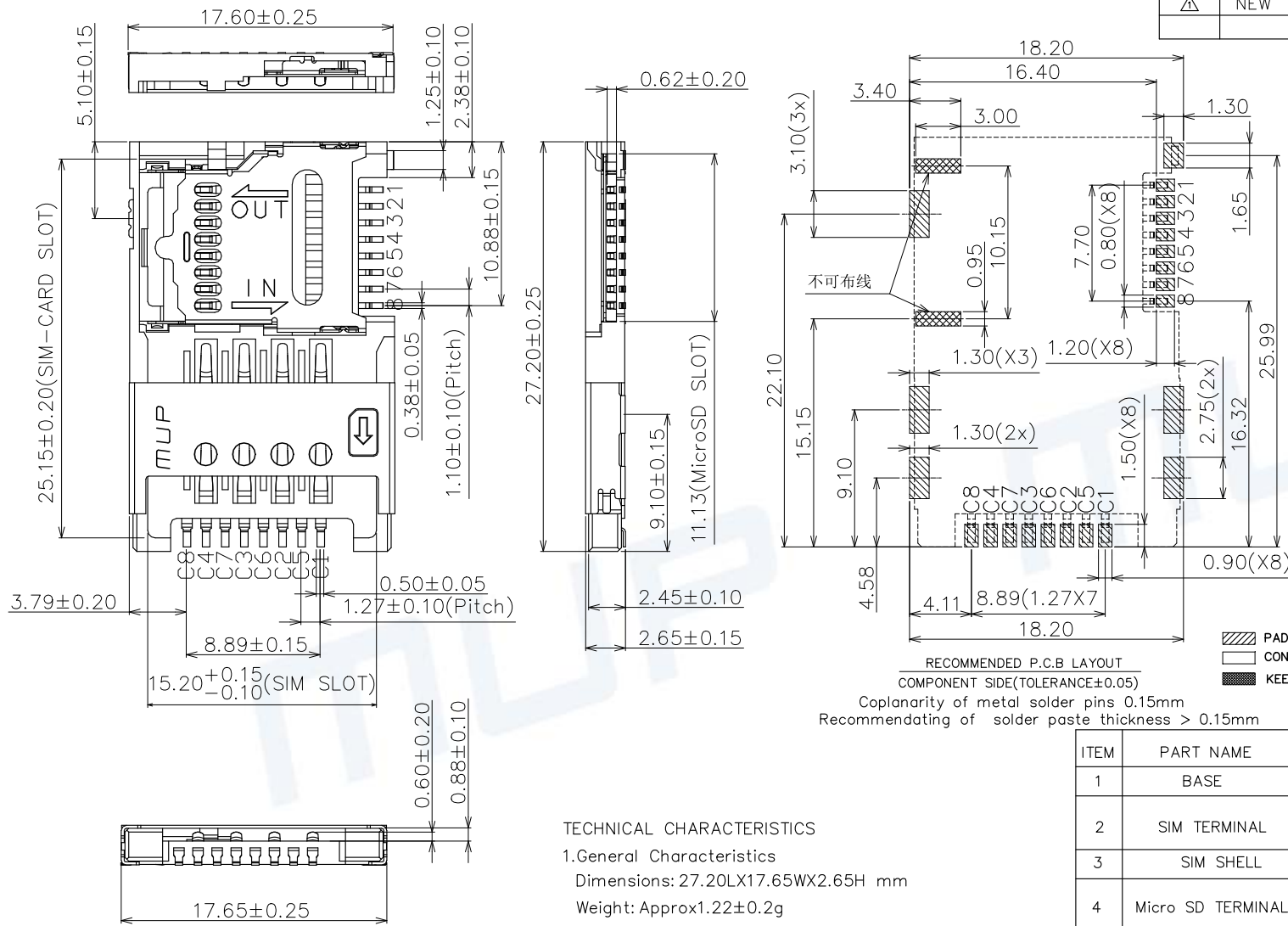


REV.	DESCRIPTION OF REVISIONS	APPR.	CHKD.	DRAW.	DATE
△	NEW			HUABO	2024/11/27



TECHNICAL CHARACTERISTICS

1.General Characteristics

Dimensions: 27.20LX17.65WX2.65H mm

Weight: Approx1.22±0.2g

Durability: 5,000 cycles min.

2.Electrical Characteristics

Contact resistance: 50mΩ typical, 100mΩ max

Insulation resistance: >1000MΩ/500V DC

3.Solderability

Vapor phase: 215°C, 30sec. Max

IR reflow: 260°C, 10sec. Max

Manual soldering: 370°C, 3sec. Max

4.Environmental Characteristics

Operating temperature: -40°C~+85°C

Operating humidity: 10%~+95%RH

Micro SD CARD		SIM CARD	
Pin No.	NAME	Pin No.	NAME
1	DAT2	C1	VCC
2	CD/DAT3	C2	RST
3	CMD	C3	CLK
4	VDD	C4	Reserved
5	CLK	C5	GND
6	VSS	C6	VPP
7	DAT0	C7	I/O
8	DAT1	C8	Reserved

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	BASE	1	Hi-temp Thermoplastic	Black UL94V-0
2	SIM TERMINAL	8	Copper Alloy	Contact area: Gold plated Solder tail: Gold plated Under plated: Ni plated
3	SIM SHELL	1	Stainless Steel	Contact area: Gold plated Under plated: Ni plated
4	Micro SD TERMINAL	8	Copper Alloy	Contact area: Gold plated Solder tail: Gold plated Under plated: Ni plated
5	HOLDER	1	Copper Alloy	Solder tail: Gold plated Under plated: Ni plated
6	Micro SD SHELL	1	Stainless Steel	

Unless otherwise specified, other tolerance are:

X	±0.35	X*	±5°
X.X	±0.25	X.X*	±4°
X.XX	±0.15	X.XX*	±3°
X.XXX	±0.10	X.XXX*	±2°

PROJ.	UNIT	SCALE
MM	1:1	

CUSTOMER DRAWING

MUP® MUP INDUSTRIAL CO.,LTD.

NAME: **2 in 1 Card Connector**

MODEL NO: **MUP-M6019-04**
Micro SD8pin+SIM8pin

DRAWN: huabo 2024/11/27

CHECKED: Zoey 2024/11/27

APPROVAL: Simon 2024/11/27

DWG NO.: DWG-M6019-04-01

SHEET 1/1

REVISION 1

